

Deep Trench Etcher
Etch Rates for Masking Materials
Bosch Recipe

January 2006 (appended June 2007)
Masking Material Etch Rate

	(Å/minute)
S1818 Photoresist	340
S1813 Photoresist	290
SPR 220-4.5 Photoresist	320
SPR 220-7 Photoresist	314
Futurrex NR5-1500P	772
Thermal Oxide	104
Regular Silicon Nitride	359
Low Stress Nitride	361
PECVD SiO ₂ deposited at 340 °C	124

These etch rates should be used as a guide. To get a more accurate etch rate you may want to do additional etch rate tests using a patterned wafer with your design.